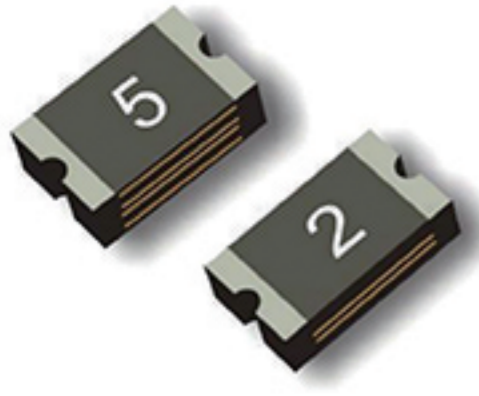


TLC-FSMD Series



Features

- Surface Mount Devices
- Standard 0603mils(1608mm) footprint
- Surface mount packaging for automated assembly
- Compatible with Pb and Pb-free solder reflow profiles.

Applications

- Mobile phones
- PC motherboards
- PDA's/Digital cameras
- USB port protection
- HDMI source protection



Electrical Characteristics(25°C)

RoHS

P/N	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	Maximum Time to trip		P _d type(w)	Resistance	
					(A)	(Sec.)		R _{min}	R _{1max}
TLC-FSMD010	0.10	0.30	15.00	40.00	0.50	1.00	0.50	0.90	6.00
TLC-FSMD020	0.20	0.50	9.00	40.00	1.00	0.60	0.50	0.55	3.50
TLC-FSMD035	0.35	0.75	6.00	40.00	8.00	0.10	0.50	0.20	1.40
TLC-FSMD050	0.50	1.00	6.00	40.00	8.00	0.10	0.50	0.10	0.80

I_H: Holding Current: maximum current at which the device will not trip in 25°C still air.

I_T: Tripping Current minimum current at which the device will trip in 25°C still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

I_{max}: Maximum fault current device can withstand without damage at rated voltage.

T_{trip}: Maximum time to trip(s) at assigned current.

P_d typ: Rated working power.

R_{min}: Minimum resistance of device prior to trip at 25°C.

R_{1max}: Maximum resistance of device measured one hour after tripping at 25°C.

Ordering Information

Series No.	Amp Code	Packaging Code	Quantity	Purchase Order No.
TLC-FSMD				

